

TECHNICAL INFORMATION OF CHANGE

PROJECT: Micro-Q

TIOC #: 15 / 001120

**ATTACH TO DOCU: D_MQBP11 (BACK PANEL PCB)
REV1.1 (12.07.00)**

PCB REV: REV1.1

COMPONENT LAYOUT: REV1.1

CHANGED BY: Th. Kircher

SUBJECT: Ellimination of hum on phones output

No. of Pages: 1

Description:

Audible hum on the phones output is caused by a high ripple on the power supply voltage. There are 2 ways to solve this problem:

A) Replacing the external power supply (Output: 12V=, 1.2A. Output voltage ripple less or equal than 100mVpp. Normally every wall mount switch mode power supply will comply with these specification)

B) Modifying the Pack Panel PCB:

Changed Values:

Part Name	Old Value	New Value	Schematic Page
C2034	470u	10u/50V	3 / B4

Omitted Parts:

Part	Value	Description	Schematic Page
R2022	10R		3 / B4

New Parts:

Part	Value	Description	Schematic Page
IC1209	7808	Regulator TO220	3 / B4

Modify-Procedure:

Replace the 470u cap by 10u cap. The length of the 10u cap leads should kept that long, that the solder pads are accessible on the component side to mount the regulator piggyback style.

Remove the smd resistor.

Solder the 7808 terminals (In,GND,Out) the following way:

In: solder to right pad of the removed R2022 (which points to the flat cable)

GND: solder to the - Pin of C2034

Out: solder to the + Pin of C2034.



FOR

electronics

Project: Micro Q / BACK PCB

Date: 19.06.00

Title: HEADPHONE AMP

Rev: 1.1

File: MQBP11B | Don by: Th.K.

SHT 3 OF 4

10

9

2

9

5

4

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10

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